

Substrate Road map ②

ベトナム第三工場 ロードマップ

Contents		Technology Roadmap (Unit: μm)		
		FY 2026	FY 2027	FY 2028
L/S Line Width/Space	Tenting (Cu thickness 13 μm)	25/30	←	←
	MSAP (Cu thickness 13 μm)	20/20	15/20	15/15
WB Pad Width/Space	Tenting (Cu thickness 13 μm)	70	←	←
	MSAP (Cu thickness 13 μm)	55	50	←
Laser Via Pitch/via Size/Pad Diameter (Annular Ring)		160/60/120 (30)	140/50/100 (25)	120/40/80 (20)
Mechanical Via Size/Pad Diameter (Annular Ring)		100/200 (50)	80/180 (50)	←
X-via	Via diameter Top/Bot	75/50	60/40	←
	Core thickness	60-200	50-100	40-100
	Specification	Filled/Dimple	←	←
Core Thickness		40	←	←
PP Thickness		20	15	←
Copper thickness		13	10	←
Coreless	Availability	○	←	←
Solder Resist	Thickness	13	←	10 (DF-SR)
	SRO Size	100	80	←
	SRR	20	15	←
	Flatness	5	←	←
	Method	Ink/DFSR	←	←
Surface Finish	Au Plating	Soft/Hard Gold, ENEPIG	←	←
	OSP	Shikoku: F2LX (PK)	←	←
Front and back misalignment		25	20	←
Total Thickness		Cored (2L) 120 Coreless (3L) 106 Coreless (4L) 121	Cored (2L) 100 Coreless (3L) 88 Coreless (4L) 121 Coreless (5L) 146 Coreless (6L) 172	Cored (2L) 90 Coreless (3L) 82 Coreless (4L) 108 Coreless (5L) 134 Coreless (6L) 160
Strip Size (Small Strip)		Min 25mm	←	←
Process		STD/EB/EBS	←	←